



- ★ Super Low Gate Charge
- ★ 100% EAS Guaranteed
- ★ Green Device Available
- ★ Excellent CdV/dt effect decline
- ★ Advanced high cell density Trench technology

Product Summary

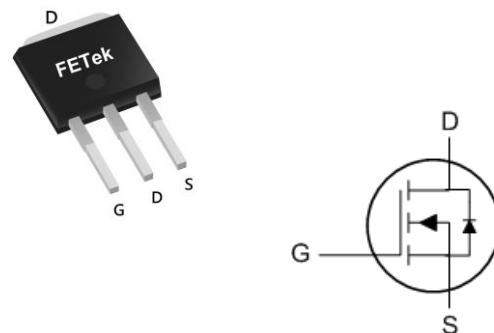
BVDSS	RDS(ON)	ID
100V	22mΩ	45A

Description

The FKR0018A is the high cell density trenched N-ch MOSFETs, which provide excellent RDS(ON) and gate charge for most of the synchronous buck converter applications.

The FKR0018A meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

TO251 Pin Configuration



Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V _{DS}	Drain-Source Voltage	100	V
V _{GS}	Gate-Source Voltage	±20	V
I _D @T _C =25°C	Continuous Drain Current, V _{GS} @ 10V ¹	45	A
I _D @T _C =100°C	Continuous Drain Current, V _{GS} @ 10V ¹	28	A
I _{DM}	Pulsed Drain Current ²	100	A
EAS	Single Pulse Avalanche Energy ³	84	mJ
I _{AS}	Avalanche Current	41	A
P _D @T _C =25°C	Total Power Dissipation ⁴	90	W
T _{STG}	Storage Temperature Range	-55 to 150	°C
T _J	Operating Junction Temperature Range	-55 to 150	°C

Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
R _{θJA}	Thermal Resistance Junction-Ambient ¹	---	62	°C/W
R _{θJC}	Thermal Resistance Junction-Case ¹	---	1.4	°C/W

Electrical Characteristics ($T_J=25\text{ }^{\circ}\text{C}$, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$, $I_D=250\mu\text{A}$	100	---	---	V
$\Delta BV_{DSS}/\Delta T_J$	BV_{DSS} Temperature Coefficient	Reference to $25\text{ }^{\circ}\text{C}$, $I_D=1\text{mA}$	---	0.096	---	$\text{V}/\text{ }^{\circ}\text{C}$
$R_{DS(ON)}$	Static Drain-Source On-Resistance ²	$V_{GS}=10\text{V}$, $I_D=30\text{A}$	---	18	22	$\text{m}\Omega$
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}$, $I_D=250\mu\text{A}$	2.5	---	4.5	V
$\Delta V_{GS(th)}$	$V_{GS(th)}$ Temperature Coefficient		---	-5.5	---	$\text{mV}/\text{ }^{\circ}\text{C}$
I_{DSS}	Drain-Source Leakage Current	$V_{DS}=80\text{V}$, $V_{GS}=0\text{V}$, $T_J=25\text{ }^{\circ}\text{C}$	---	---	1	μA
		$V_{DS}=80\text{V}$, $V_{GS}=0\text{V}$, $T_J=55\text{ }^{\circ}\text{C}$	---	---	5	
I_{GSS}	Gate-Source Leakage Current	$V_{GS}=\pm 20\text{V}$, $V_{DS}=0\text{V}$	---	---	± 100	nA
g_{fs}	Forward Transconductance	$V_{DS}=5\text{V}$, $I_D=30\text{A}$	---	27	---	S
R_g	Gate Resistance	$V_{DS}=0\text{V}$, $V_{GS}=0\text{V}$, $f=1\text{MHz}$	---	1.9	3.8	Ω
Q_g	Total Gate Charge (10V)	$V_{DS}=80\text{V}$, $V_{GS}=10\text{V}$, $I_D=30\text{A}$	---	27.6	38.6	nC
Q_{gs}	Gate-Source Charge		---	11.4	16	
Q_{gd}	Gate-Drain Charge		---	7.9	11.1	
$T_{d(on)}$	Turn-On Delay Time	$V_{DD}=50\text{V}$, $V_{GS}=10\text{V}$, $R_G=3.3\Omega$, $I_D=30\text{A}$	---	15.6	31.2	ns
T_r	Rise Time		---	17.2	31	
$T_{d(off)}$	Turn-Off Delay Time		---	16.8	33.6	
T_f	Fall Time		---	9.2	18.4	
C_{iss}	Input Capacitance	$V_{DS}=15\text{V}$, $V_{GS}=0\text{V}$, $f=1\text{MHz}$	---	1890	2645	pF
C_{oss}	Output Capacitance		---	268	375	
C_{rss}	Reverse Transfer Capacitance		---	67	94	

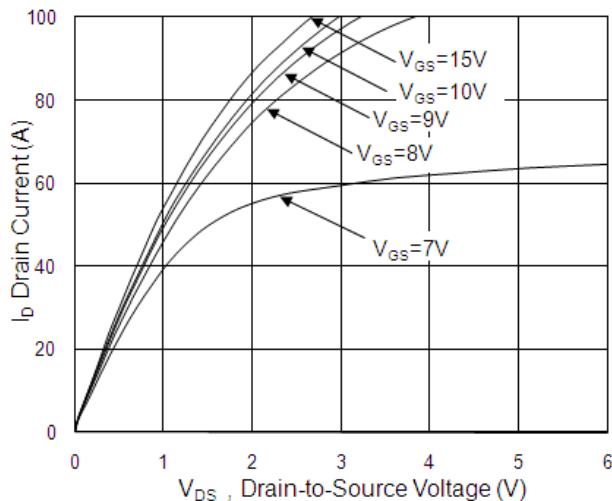
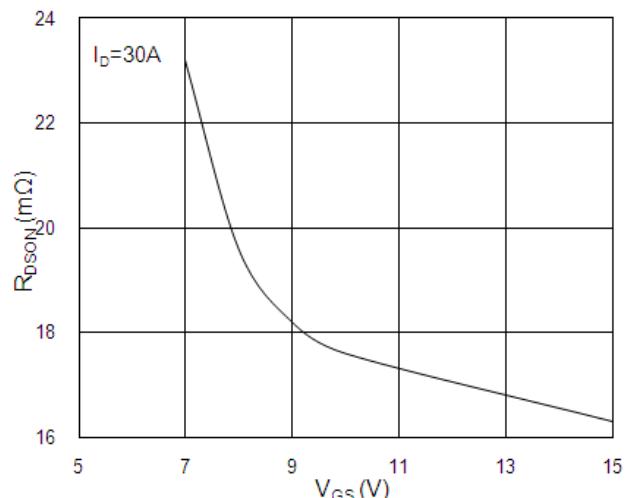
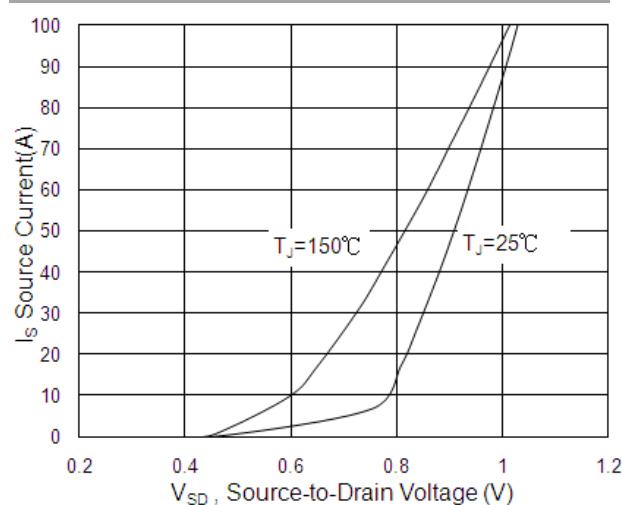
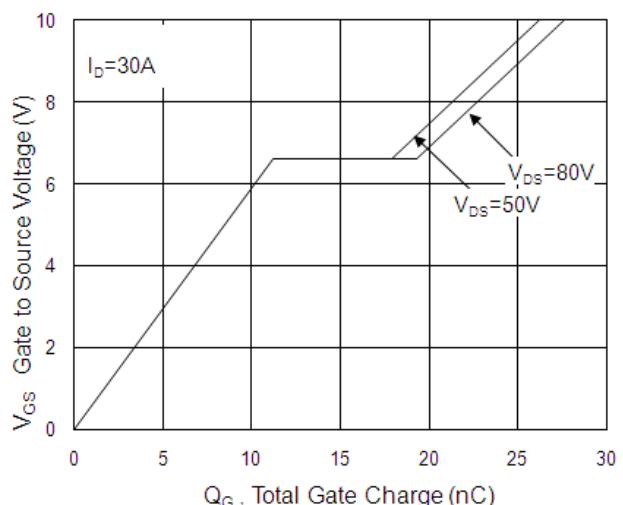
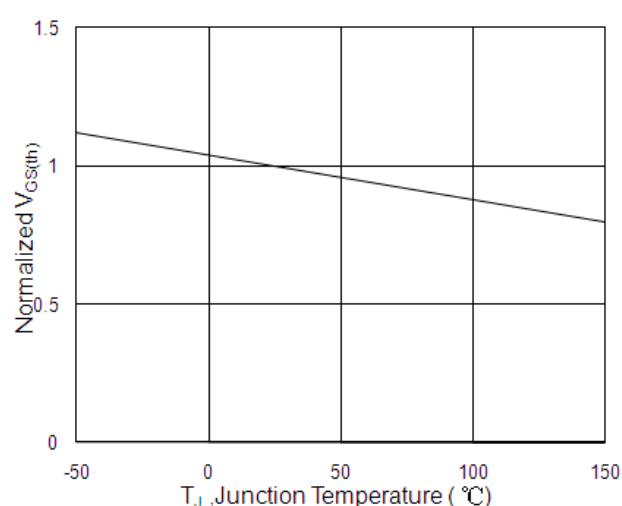
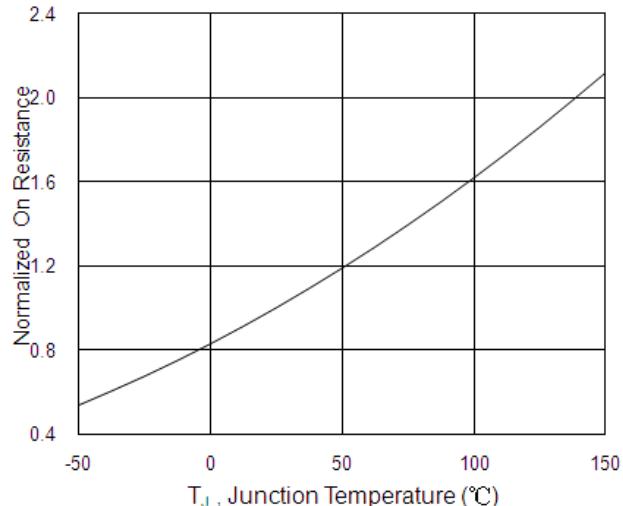
Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_s	Continuous Source Current ^{1,5}	$V_G=V_D=0\text{V}$, Force Current	---	---	45	A
I_{SM}	Pulsed Source Current ^{2,5}		---	---	100	A
V_{SD}	Diode Forward Voltage ²	$V_{GS}=0\text{V}$, $I_s=1\text{A}$, $T_J=25\text{ }^{\circ}\text{C}$	---	---	1.2	V
t_{rr}	Reverse Recovery Time	$I_F=30\text{A}$, $dI/dt=100\text{A}/\mu\text{s}$, $T_J=25\text{ }^{\circ}\text{C}$	---	34	---	nS
Q_{rr}	Reverse Recovery Charge		---	47	---	nC

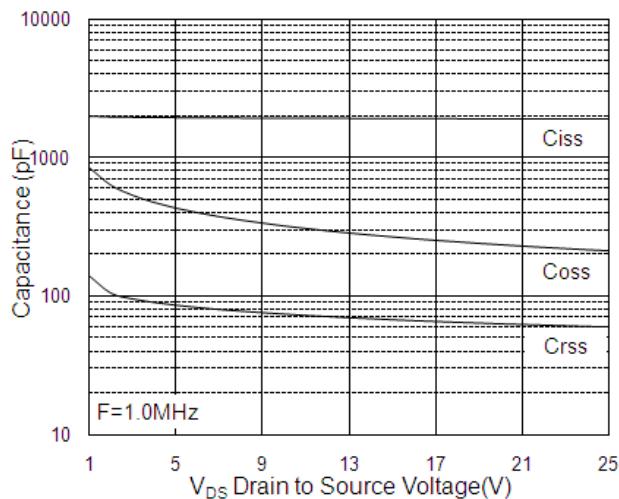
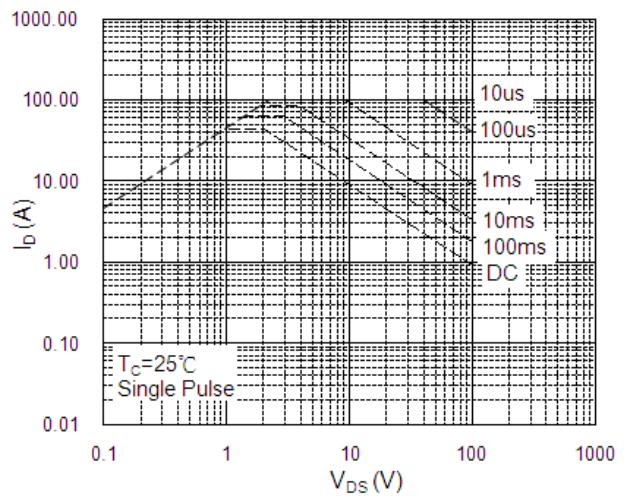
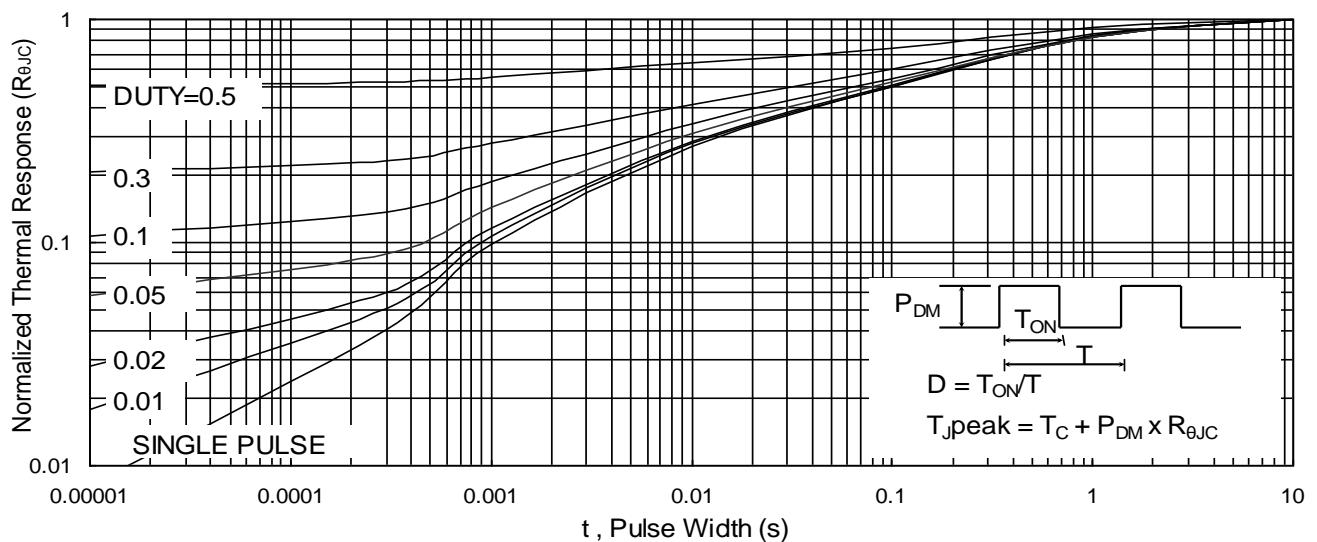
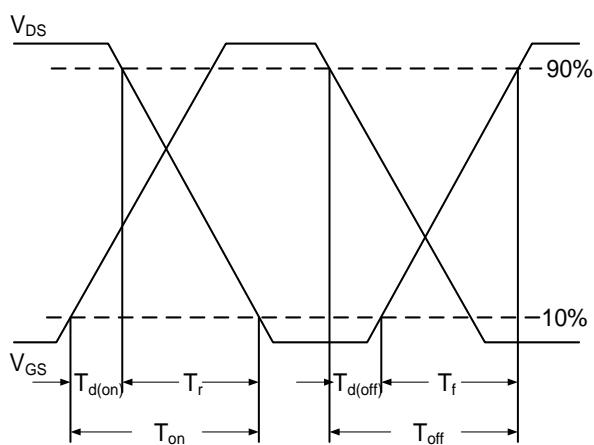
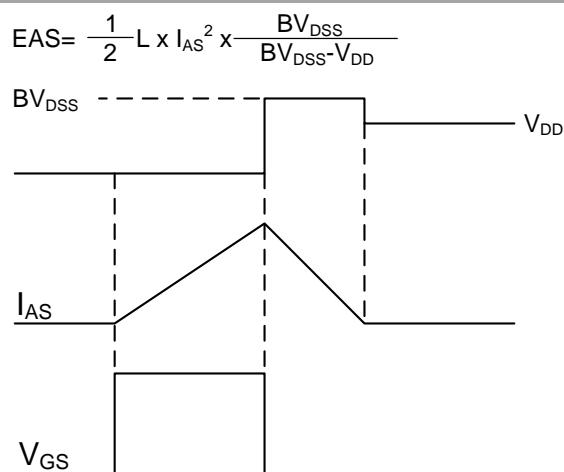
Note :

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is $V_{DS}=25\text{V}$, $V_{GS}=10\text{V}$, $L=0.1\text{mH}$, $I_{AS}=41\text{A}$
- 4.The power dissipation is limited by $150\text{ }^{\circ}\text{C}$ junction temperature
- 5.The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.

Typical Characteristics


Fig.1 Typical Output Characteristics

Fig.2 On-Resistance vs G-S Voltage

Fig.3 Source Drain Forward Characteristics

Fig.4 Gate-Charge Characteristics

Fig.5 Normalized $V_{GS(th)}$ vs T_J

Fig.6 Normalized $R_{DS(on)}$ vs T_J

Data and specifications subject to change without notice.
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Fig.7 Capacitance

Fig.8 Safe Operating Area

Fig.9 Normalized Maximum Transient Thermal Impedance

Fig.10 Switching Time Waveform

Fig.11 Unclamped Inductive Switching Waveform